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Teradyne Unveils Magnum 7H - The Next-Generation Memory Tester for High Bandwidth Memory Devices

NORTH READING, Mass.--(BUSINESS WIRE)-- Teradyne, Inc. (NASDAQ: TER), a leading provider of...
NORTH READING, Mass.--(BUSINESS WIRE)-- Teradyne, Inc. (NASDAQ: TER), a leading provider of automated test equipment and advanced robotics, is proud to announce the launch of the Magnum 7H, a next-generation memory tester designed to meet the rigorous demands of testing high bandwidth memory (HBM) devices, integrated with GPUs and accelerators in high-performance, generative AI servers. The Magnum 7H is engineered to deliver high-parallelism, high-speed, and high-accuracy testing for HBM stacked die at scale. Volume shipments and HBM device production on Teradyne's Magnum 7H have started ramping at the largest HBM manufacturers in the industry.

This press release features multimedia. View the full release here:
https://www.businesswire.com/news/home/20250804458862/en/

Teradyne Magnum 7H High Bandwidth Memory Tester: next-generation memory tester designed to meet the rigorous demands of testing high bandwidth memory (HBM) devices, integrated with GPUs and accelerators in high-performance, generative AI servers.

"We are thrilled to introduce the Magnum 7H, a revolutionary memory tester that sets a new standard for testing HBM devices," said Young Kim, President, Memory Test Division, Teradyne. "This innovation represents a significant milestone in our commitment to advancing memory test technology and delivering a tester that not only supports today's devices but is future-proofed for tomorrow's devices as well."

The Magnum 7H is a cutting-edge memory tester that supports a wide range of HBM versions, including HBM2E, HBM3, HBM3E, HBM4, and HBM4E. It offers comprehensive test coverage, from base-die wafer test to memory core test and burn-in, ensuring the quality and reliability of HBM devices. Additionally, the Magnum 7H supports testing of pre-singulated HBM devices at the Known-Good-Stack-Die (KGSD) or Chip-on-Wafer level with traditional probers and probe cards, as well as post-singulated HBM with new bare-die

probers/handlers for improved device quality.

The Teradyne Magnum 7H delivers:

*Enhanced Device Quality: S*uperior DPS response time delivers higher device yield.
Comprehensive Memory and Logic Testing: Magnum 7H is ideally suited for testing HBM stacks that contain both logic base dies and DRAM dies. It delivers high-speed memory testing with a flexible algorithmic pattern generator (APG) and logic testing with our Logic Vector Memory (LVM) option. The Fail List Streaming (FLS) feature ensures high-speed error capture for both memory and logic testing.
High Performance: High-speed testing of current HBM3/3E and next-generation HBM4/4E devices up to 4.5Gbps.
High Parallelism: Essential for lowering overall cost-of-test for HBM, the Magnum 7H is configurable for up to 9,216 digital pins and 2,560 power pins, enabling superior touchdown efficiency at probe and resulting in 1.6x increased throughput in mass production environments.
The increasing demands for higher performance and efficiency in AI and cloud infrastructure applications are driving demand for HBM. Teradyne's Magnum 7H is a next-generation memory tester engineered to test both today and tomorrow's HBM devices with high parallelism, speed, and accuracy, across the entire manufacturing process.

Find us at FMS 2025, booth 646 to learn more about Magnum 7H and our comprehensive portfolio of memory test products. For more information about the Magnum 7H and its capabilities, visit https://www.teradyne.com/products/magnum-7h/.

About Teradyne
Teradyne (NASDAQ:TER) designs, develops, and manufactures automated test equipment and advanced robotics systems. Its test solutions for semiconductors and electronics products enable Teradyne's customers to consistently deliver on their quality standards. Its advanced robotics business includes collaborative robots and mobile robots that support manufacturing and warehouse operations for companies of all sizes. For more information, visit teradyne.com. Teradyne® is a registered trademark of Teradyne, Inc., in the U.S. and other countries.

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